

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the Application of:

Inventors

Alexander Leybovich

Serial No.

10/624,384

Filed

July 22, 2003

Title

Method and Apparatus for Deposition

Of Low-K Dielectric Materials

Docket No.

020324 227P2

Customer No.:

33805

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

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Pursuant to 37 C.F.R. 1.56, the attention of the Patent and Trademark Office is hereby directed to the reference(s) listed on the attached PTO/SB/08A. One copy of each reference is attached. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the reference(s) be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This information disclosure statement, filed in accordance with 37 C.F.R. 1.97, shall not be construed as a representation that a search has been made. Further, the filing of this information disclosure statement shall not be construed to be an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. 1.56(b)

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1. This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

Respectfully submitted,

Danielle A. Skoczen

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216-642-3342

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INFORMATION DI	SCL	OSURE	Application Number	10/624,384	
STATEMENT BY APPLICANT (use as many sheets as necessary)			Filing Date	July 22, 2003	
			First Named Inventor	Leybovich	
			Art Unit		
			Examiner Name		
Sheet 1	of	3	Attorney Docket Number	020324 227P2	

	U.S. PATENT DOCUMENTS				
Examiner Initials*	Cite No. ¹	<u>Document Number</u> Number - Kind Code ² (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
	AA	US-6,395,649	05-28-2002	Wu, Hui-Jung	
	AB	US-6,340,435	01-22-2002	Bjorkman et al.	
	AC	US-			
	AD	US-			
	AE	US-			
	AF	US-			
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	АН	US-			
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FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No. ¹	Foreign Patent Document Country - Number - KindCode Code (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁶

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Examiner Signature	Date Considered	



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